

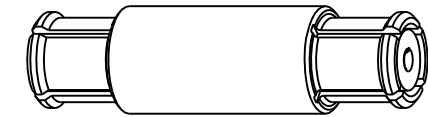
NOTES:

1. MATERIALS AND FINISHES:
 - BODY - BeCu, GOLD PLATING, .000030 [0.8] THICK OVER NICKEL
 - CONTACT - BeCu, GOLD PLATING, .000030 [0.8] THICK OVER NICKEL
 - INSULATOR - PTFE
2. ELECTRICAL:
 - A. IMPEDANCE: 50 OHM
 - B. FREQUENCY RANGE: DC - 26.5 GHz
 - C. VSWR(RETURN LOSS): 1.2 (20.8 dB), MAX. DC-10GHz
 1.4 (15.6 dB), MAX. 10-18GHz
 1.5 (14 dB), MAX. 18-26.5GHz
 - D. DIELECTRIC WITHSTANDING VOLTAGE: 500 VRMS, MIN.
3. PHYSICAL:
 - A. DURABILTIY: 100 CYCLES MIN.
 - B. ENGAGEMENT FORCE: 15 LB [67 N] MAX
 - C. DISINGAGEMENT FORCE: 2 LB [9 N] MIN
 - E. TEMERATURE RANGE: -65° C TO 165° C
4. PACKAGING:
 - A. QUANTITY: SINGLE PACK
 - B. MARKING: AMPHENOL, SMP-FSBA-131, DATE CODE

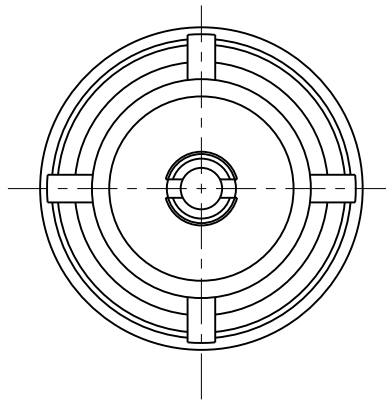
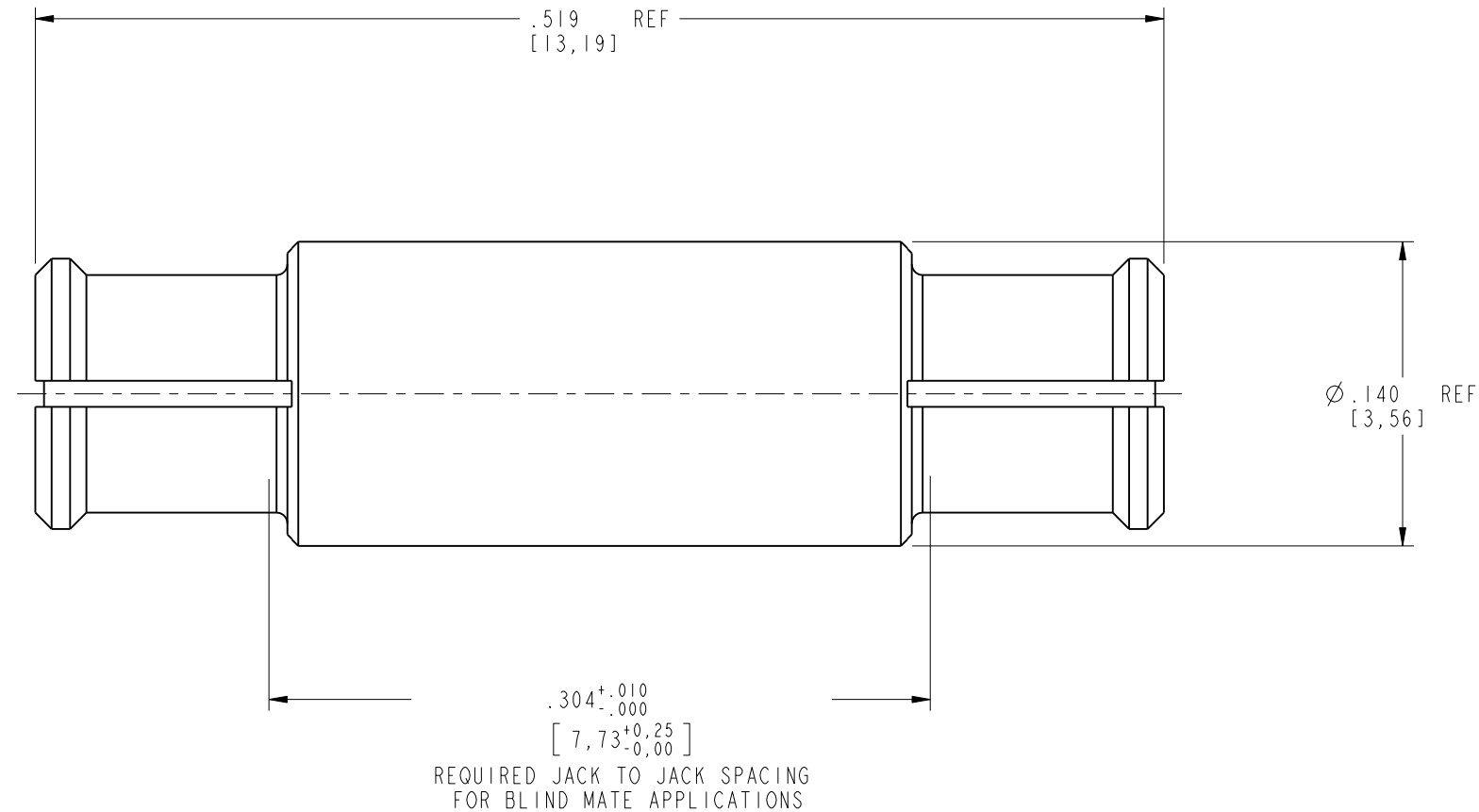
THIRD ANGLE PROJ.

REVISIONS

REV	DESCRIPTION	DATE	ECO	APPR
A	RELEASE TO MFG	6/25/09	47636	TRC



SCALE 4.000



CUSTOMER OUTLINE DRAWING

ALL OTHER SHEETS ARE FOR INTERNAL USE ONLY

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN METRIC AND TOLERANCES ARE: <0.5mm ±0.05mm 0.5 - 6mm ±0.1mm 6 - 30mm ±0.2mm 30 - 120mm ±0.3mm ANGLES ±1°	MATERIAL	DRAWN K.LI	DATE 15-May-09	TITLE ASSEMBLY SMP, M-M	Amphenol RF Danbury CT USA, Tainan, Taiwan, Shenzhen, China www.amphenolrf.com	
	REFERENCE EAR # 1919 AND 615X-1718	ENGINEER T. COVERSTONE	DATE 15-May-09			
	CONFIGURATION LEVEL: Prototype	APPROVED K. CAPOZZI	DATE 6/25/09	SCALE: 12.0:1.0 SHEET 2 OF 2	ITEM NO. SMP-FSBA-131	
	FINISH	Root Folder/SMP/SMP-FSBA-131	DWG SIZE B	REV A	PART NO. SMP-FSBA-131	

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